Application:

WLAN, 802.11b/g, Bluetooth, etc...

Features

SMD, high reliability, ultra Impact, Omni-directional...

Part number

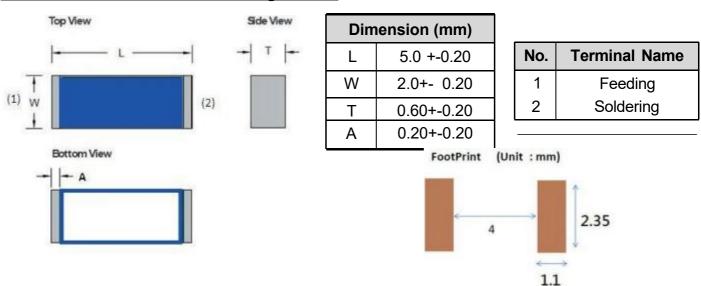
HLX	502006	D08	R	245		
(1)	(2)	(3)	(4)	(5)		
(1)Product Model			SURL			
(2) Size Code			5.0x2.	5.0x2.0x0.6mm		
(3) Type Code			D08			
(4) Packing			Tape a	Tape and reel		
(5) Frequency			2.45G	Hz		

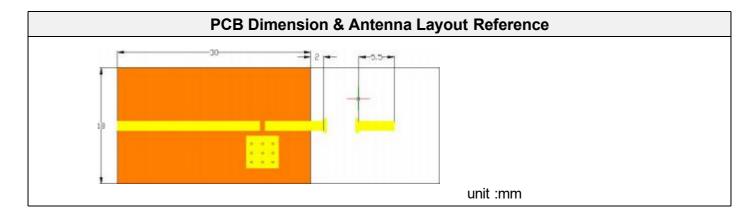
Electrical Specification

Working Frequency Range	2400 ~2484 MHz
Peak Gain	3.5dBi (Typ.)
Impedance	50 Ohm
Return loss	10 dB(Min)
Polarization	Linear
Azimuth Beamwidth	Omni-directional
Operation Temperature(°C)	-40 ~85℃

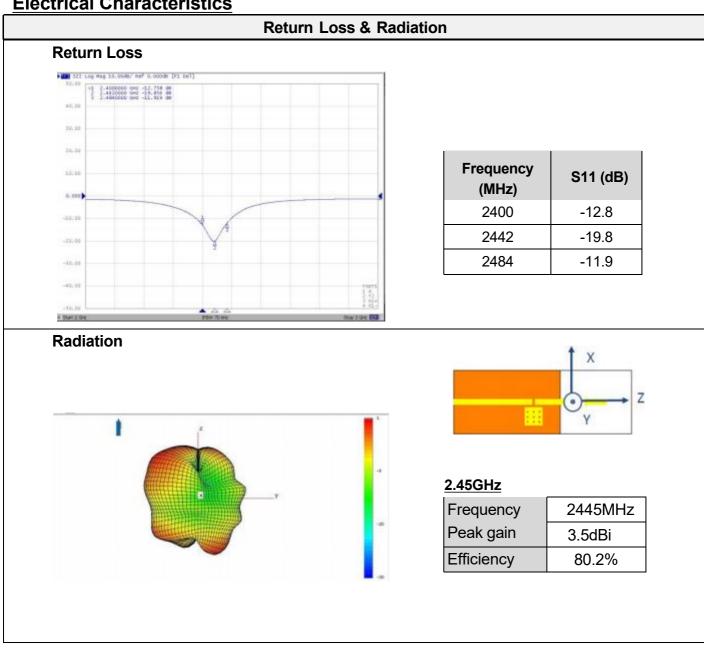
The specification is defined on EVB.

Dimension and Terminal Configuration





Electrical Characteristics

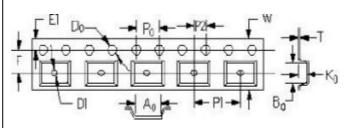


Reel

Checking note	Index	Spec (mm)
Internal diameter of reel	Α	60.20 : 0.50
External diameter of reel	В	178: 1.00

Quantity/per reel	3000 pcs	
	Plastic	
Tape material	(embossed)	

Taping Blister Tape



Checking note	Index	Spec (mm)
Sprocket hole	D0	1.50 +0.10/-0.00
Distance sprocket hole to outside	E1	1.75 : 0.10
Distance sprocket hole to pocket	F	5.50: 0.05
Distance sprocket hole to sprocket hole	P0	4.00: 0.10
Distance pocket to pocket	P1	4.00: 0.10
Distance sprocket hole to pocket	P2	2.00: 0.05
Tape width	W	12.00 +0.30/-0.10
Pocket width nominal clearance	A0	2.28 : 0.13
Pocket length nominal clearance	В0	5.70 : 0.13
Pocket depth minimum clearance	K0	1.58 : 0.10
Thickness of tape	Т	0.23: 0.02

Test Item	Procedure	Requirements Ceramic Type	Remark (Reference)
Electrical Characterization		Fulfill the electrical specification	User Spec.
Thermal Shock	1. Preconditioning: 50 ± 10°C / 1 hr , then keep for 24 ± 1 hrs at room temp. 2. Initial measure: Spec: refer Initialspec. 3. Rapid change of temperature test: -30°C to +85°C; 100cycles; 15 minutes at Lower category temperature; 15 minutes at Upper category temperature.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 107
Temperature Cycling	 Initial measure: Spec: refer Initialspec. 100 Cycles (-30°C to +85°C), Soak Mode=1 (2 Cycle/hours). Measurement at 24 ± 2Hours after test condition. 	No Visible Damage. Fulfill the electrical specification.	JESD22 JA104
High Temperature Exposure 1. Initial measure: Spec: refer Initialspec. 2. Unpowered; 500hours @ T=+85°C. 3. Measurement at 24 ± 2 hours after test.		No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Low Temperature Storage	Initial measure: Spec: refer Initialspec. Unpowered: 500hours @ T=-30℃. Measurement at 24 ± 2 hours after test.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Solderability (SMD Bottom Side)	Dipping method: a. Temperature: 235 \pm 5 \circ C b. Dipping time: 3 \pm 0.5s	The solder should cover over 95% of the critical area of bottom side.	IEC 60384-21/22 4.10
Soldering Heat Preheating temperature: 150 ± 10 °C. Preheating time: $1 \sim 2 \text{ min}$. Solder temperature: 260 ± 5 °C. Dipping time: 5 ± 0.5 s		No Visible Damage.	IEC 60384-21/22 4.10
Vibration 5g's for 20 min., 12 cycles each of 3 orientations Note: Use 8"X5" PCB .031" thick 7 secure points on, of side and 2 secure points at corners of opposite sides mounted within 2" from any secure point. Test from 1		No Visible Damage.	MIL-STD-202 Method 204
Mechanical Shock	Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen(18 shocks) Peak value: 1,500g's Duration: 0.5ms Velocity change:15.4 ft/s Waveform: Half-sine	No Visible Damage.	MIL-STD-202 Method 213
Humidity Bias	1. Humidity: 85% R.H., Temperature: 85 \pm 2 $_{\circ}$ C. 2. Time: 500 \pm 24 hours. 3. Measurement at 24 \pm 2hrs after test condition.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 Method 106

Board Flex (SMD)	1. Mounting method: IR-Reflow. PCB Size (L:100 × W:40 × T:1.6mm) 2. Apply the load in direction of the arrow until bending reaches 2 mm.	No Visible Damage.	AEC-Q200 005
Adhesion	Force of 1.8Kg for 60 seconds. radius 0,5 mm DUT wide thickness shear force	No Visible Damage Magnification of 20X or greater maybe employed for inspection of the mechanical integrity of the device body terminals and body/terminal junction.	AEC-Q200 006
Physical Dimension	Any applicable method using x10 magnification, micrometers, calipers, gauges, contour projectors, or other measuring equipment, capable of determining the actual specimen dimensions.	In accordance with specification.	JESD22 JB100

Revision History

Revision	Date	Content
1	2019/7/20	New issue